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International Bureau

INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(51) International Patent Classification 6 : H05K 1/03 — A1

(11) International Publication Number: **WO 00/07417**

(43) International Publication Date: 10 February 2000 (10.02.00)

(21) International Application Number: PCT/US99/17300

(22) International Filing Date: 30 July 1999 (30.07.99)

(30) Priority Data:

09/127,580	31 July 1998 (31.07.98)	US
09/127,579	31 July 1998 (31.07.98)	US
60/097,140	19 August 1998 (19.08.98)	US
60/097,169	19 August 1998 (19.08.98)	US
09/172,178	13 October 1998 (13.10.98)	US
09/191,594	13 November 1998 (13.11.98)	US
09/363,959	29 July 1999 (29.07.99)	US

(71) Applicant: KULICKE & SOFFA HOLDINGS, INC. [US/US]; 2101 Blair Mill Road, Willow Grove, PA 19090 (US).

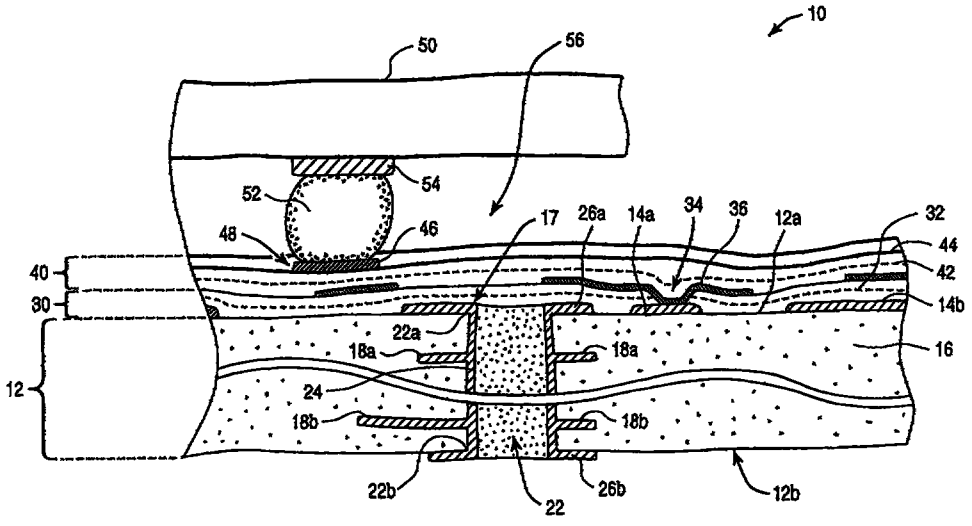
(72) Inventors: STRANDBERG, Jan, I.; 21327 Glen Place #6, Cupertino, CA 95014 (US). CHAZAN, David, J.; 4040 Manzana Lane, Palo Alto, CA 94306 (US). SKINNER, Michael, P.; 5444 Century Meadow Court, San Jose, CA 95111 (US).

(74) Agents: BROOKS, Kenneth, C. et al.; Townsend and Townsend and Crew LLP, 8th Floor, Two Embarcadero Center, San Francisco, CA 94111-3834 (US).

(81) Designated States: AE, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, CA, CH, CN, CU, CZ, DE, DK, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MD, MG, MK, MN, MW, MX, NO, NZ, PL, PT, RO, RU, SD, SE, SG, SI, SK, SL, TJ, TM, TR, TT, UA, UG, UZ, VN, YU, ZA, ZW, ARIPO patent (GH, GM, KE, LS, MW, SD, SL, SZ, UG, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, CH, CY, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GW, ML, MR, NE, SN, TD, TG).

Published
With international search report.

(54) Title: LOW-IMPEDANCE HIGH-DENSITY DEPOSITED-ON-LAMINATE STRUCTURES HAVING REDUCED STRESS



(57) Abstract

Low-impedance high-density deposited-on-laminate (DONL) structures having reduced stress features reducing metallization present on the laminate printed circuit board. In this manner, reduced is the force per unit area exerted on the dielectric material disposed adjacent to the laminate material that is typically present during thermal cycling of the structure.